Single 2-Input NOR Gate

The NL17SV02 is an ultra-high performance 2–Input NOR gate manufactured in 0.35 μm technology, with excellent performance down to 0.9 V. This device is ideal for extremely high speed and high-drive applications. Additionally, limitations of board space are no longer a constraint. The very small SOT–553 makes this device fit most tight designs and spaces.

Features

- Extremely High Speed: $t_{PD} = 1.0 \text{ ns (Typ)} @ V_{CC} = 3.3 \text{ V}$
- Designed for 0.9 to 3.6 V Operation
- Overvoltage Tolerance (OVT)* Input Pins Permits Logic Translation
- Balanced ±24 mA Output Drive @ V_{CC} 3.3 Volts
- Near Zero Static Supply Current
- Ultra-Tiny SOT-553 5 Pin Package only 1.6 x 1.6 x 0.6 mm
- These Devices are Pb-Free and are RoHS Compliant

Typical Applications

- Cellular
- Digital Camera
- PDA
- Digital Video

Industry Leadership

• Functionally Similar to NC7SV02 and SN74AUC1G02

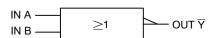


Figure 1. Logic Symbol

FUNCTION TABLE

Inp	Output		
Α	A B		
L	L	Н	
L	Н	L	
Н	L	L	
Н	Н	L	



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UK M •

MARKING

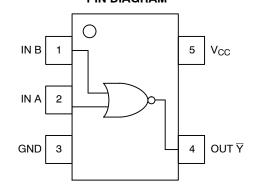
UK = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

PIN DIAGRAM



PIN ASSIGNMENT

PIN#	FUNCTION
1	IN B
2	IN A
3	GND
4	OUT ₹
5	V _{CC}

ORDERING INFORMATION

Device	Package	Shipping†
NL17SV02XV5T2G	SOT-553 (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}Overvoltage Tolerance (OVT) enables input pins to function outside (higher) of their operating voltages, with no damage to the devices or to signal integrity.

MAXIMUM RATINGS

Symbol	Rating	Value	Units	
V _{CC}	DC Supply Voltage	-0.5 to +4.6	V	
VI	DC Input Voltage	-0.5 to +4.6	V	
Vo	DC Output Voltage	-0.5 to V _{CC} +0.5	V	
lικ	DC Input Diode Current V _{IN} < 0 V	-50	mA	
l _{OK}	DC Output Diode Current VOUT < 0 V VOUT > VCC	-50 +50	mA	
I _O	DC Output Sink Current ±50		mA	
Icc	DC Supply Current per Supply Pin	±50	mA	
I _{GND}	DC Ground Current per Ground Pin	±50	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1.0 mm from Case for 10 seconds	260	°C	
TJ	Junction Temperature Under Bias	+150	°C	
$\theta_{\sf JA}$	Thermal Resistance (Note 1)	250	°C/W	
P_{D}	Power Dissipation in Still Air at 85°C	250	mW	
MSL	Moisture Sensitivity	Level 1		
F _R	Flammability Rating Oxygen index: 28 to 34	UL 94 V-0 @ 0125 in		
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3)	3000 200	V	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
 Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V _{CC}	Positive DC Supply Voltage	0.9	3.6	٧
V _{IN}	Digital Input Voltage	0	3.6	V
V _{out}	Output Voltage	0	V _{CC}	٧
I _{OH} /I _{OL}	Output Current V _{CC} = 3.0 V to 3.6 V V _{CC} = 2.3 V to 2.7 V V _{CC} = 1.65 V to 1.95 V V _{CC} = 1.4 V to 1.6 V V _{CC} = 1.1 V to 1.3 V V _{CC} = 0.9 V		±24 ±18 ±6 ±4 ±2 ±0.1	mA
t _A	Operating Temperature Range. All Package Types	-40	+85	°C
t _r , t _f	Input Rise or Fall Time $V_{CC} = 3.3V \pm 0.3 V$	0	10	nS/V

DC CHARACTERISTICS- Digital Section (Voltages Referenced to GND)

				T _A =	25°C	T _A = -40) to 85°C	
Symbol	Parameter	Condition	v_{cc}	Min	Max	Min	Max	Units
V _{IH}	High Level Input Voltage		$\begin{array}{c} 0.90 \\ 1.10 \leq V_{CC} \leq 1.30 \\ 1.40 \leq V_{CC} \leq 1.60 \\ 1.65 \leq V_{CC} \leq 1.95 \\ 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$	0.65 x V _{CC} 0.65 x V _{CC} 0.65 x V _{CC} 0.65 x V _{CC} 1.6 2.0		0.65 x V _{CC} 0.65 x V _{CC} 0.65 x V _{CC} 0.65 x V _{CC} 1.6 2.0		V
V _{IL}	Low Level Input Voltage		$\begin{array}{c} 0.90 \\ 1.10 \leq V_{CC} \leq 1.30 \\ 1.40 \leq V_{CC} \leq 1.60 \\ 1.65 \leq V_{CC} \leq 1.95 \\ 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$		0.35 x V _{CC} 0.35 x V _{CC} 0.35 x V _{CC} 0.35 x V _{CC} 0.7 0.8		0.35 x V _{CC} 0.35 x V _{CC} 0.35 x V _{CC} 0.35 x V _{CC} 0.7 0.8	V
V _{OH}	High Level Output Voltage	I _{OH} = -100 μA	$\begin{array}{c} 0.90 \\ 1.10 \leq V_{CC} \leq 1.30 \\ 1.40 \leq V_{CC} \leq 1.60 \\ 1.65 \leq V_{CC} \leq 1.95 \\ 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$	V _{CC} - 0.1 V _{CC} - 0.1 V _{CC} - 0.2 V _{CC} - 0.2 V _{CC} - 0.2 V _{CC} - 0.2		V _{CC} - 0.1 V _{CC} - 0.1 V _{CC} - 0.2 V _{CC} - 0.2 V _{CC} - 0.2 V _{CC} - 0.2		V
		$I_{OH} = -2.0 \text{ mA}$	$1.10 \le V_{CC} \le 1.30$	0.75 x V _{CC}		0.75 x V _{CC}		
		$I_{OH} = -4.0 \text{ mA}$	$1.40 \le V_{CC} \le 1.60$	0.75 x V _{CC}		0.75 x V _{CC}		
		I _{OH} = -6.0 mA	$\begin{array}{c} 1.65 \leq V_{CC} \leq 1.95 \\ 2.30 \leq V_{CC} \leq 2.70 \end{array}$	1.25 2.0		1.25 2.0		
		I _{OH} = -12 mA	$\begin{array}{c} 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$	1.8 2.2		1.8 2.2		
		I _{OH} = -18 mA	$\begin{array}{c} 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$	1.7 2.4		1.7 2.4		
		I _{OH} = -24 mA	$2.70 \le V_{CC} \le 3.60$	2.2		2.2		
V _{OL}	Low Level Output Voltage	Ι _{ΟL} = 100 μΑ	$\begin{array}{c} 0.90 \\ 1.10 \leq V_{CC} \leq 1.30 \\ 1.40 \leq V_{CC} \leq 1.60 \\ 1.65 \leq V_{CC} \leq 1.95 \\ 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$		0.1 0.1 0.2 0.2 0.2 0.2		0.1 0.1 0.2 0.2 0.2 0.2	<
		I _{OL} = 2.0 mA	$1.10 \le V_{CC} \le 1.30$		0.25 x V _{CC}		0.25 x V _{CC}	
		I _{OL} = 4.0 mA	1.40 ≤ V _{CC} ≤ 1.60		0.25 x V _{CC}		0.25 x V _{CC}	
		I _{OL} = 6.0 mA	$1.65 \le V_{CC} \le 1.95$		0.3		0.3	
		I _{OL} = 12 mA	$\begin{array}{c} 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$		0.4 0.4		0.4 0.4	
		I _{OL} = 18 mA	$\begin{array}{c} 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$		0.6 0.4		0.6 0.4	
		I _{OL} = 24 mA	$2.70 \le V_{CC} \le 3.60$		0.55		0.55	
I _{IN}	Input Leakage Current	0 = V _I = 3.6 V	0.90 to 3.60		±0.1		±0.9	μΑ
I _{OFF}	Power Off Leakage Current		0		1		5	μΑ
Icc	Quiescent Supply Current	$V_I = V_{CC}$ or GND	0.90 to 3.60		0.9		5	μΑ

AC CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

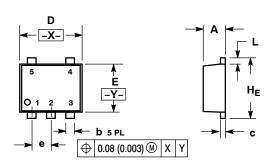
		-40°C			25°C			85°C	
Symbol	Parameter	Condition	V _{CC}	Min	Тур	Max	Min	Max	Units
T _{PHL,}	Propagation Delay	C_L = 15 pF, R_L = 1.0 M Ω	0.90		13				nS
T _{PLH}		C_L = 15 pF, R_L = 2.0 k Ω	$1.10 \le V_{CC} \le 1.30$ $1.40 \le V_{CC} \le 1.60$	3.0 1.0	6.0 3.2	15 8.7	1.0 1.0	18.6 9.7	nS
		C_L = 30 pF, R_L = 500 Ω	$\begin{array}{c} 1.65 \leq V_{CC} \leq 1.95 \\ 2.30 \leq V_{CC} \leq 2.70 \\ 2.70 \leq V_{CC} \leq 3.60 \end{array}$	1.0 0.8 0.7	2.0 1.2 1.0	6.0 4.1 3.3	1.0 0.7 0.6	6.8 4.7 4.0	nS
C _{IN}	Input Capacitance		0		2.0				pF
C _{OUT}	Output Capacitance		0		4.5				pF
C _{PD}	Power Dissipation Capacitance	$V_I = 0 \text{ V or } V_{CC}$ F = 10 MHz	0.90 to 3.60		20				pF

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction, Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

PACKAGE DIMENSIONS

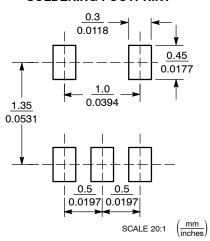
SOT-553, 5 LEAD CASE 463B-01 **ISSUE B**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			MILLIMETERS INCHE			INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX		
Α	0.50	0.55	0.60	0.020	0.022	0.024		
b	0.17	0.22	0.27	0.007	0.009	0.011		
С	0.08	0.13	0.18	0.003	0.005	0.007		
D	1.50	1.60	1.70	0.059	0.063	0.067		
E	1.10	1.20	1.30	0.043	0.047	0.051		
е		0.50 BSC		0.020 BSC				
L	0.10	0.20	0.30	0.004	0.008	0.012		
HE	1.50	1.60	1.70	0.059	0.063	0.067		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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